# RBSP EFW <br> Digital Control Board (DCB) Specification 

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| B | 6/2708 | Added Overcurrent Circuit Polarity, removed text more relevant in FPGA or FSW speciification |  |
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TBDs

| Identifier | Description |
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## Reference Documents

| Doc Number | Title |
| :--- | :--- |
| RBSP_EFW_DCB_001 | DCB FPGA Specification |
| RBSP_EFW_DCB_002 | DCB IP Core Document |
| RBSP_EFW_FSW_001 | FSW Specification |
| APL-7417-9083 | EFW ICD |
| RBSP_EFW_ FSW_005 | EFW Command and Telemetry Document |
| RBSP_EFW_BPL_001 | EFW IDPU Backplane Specification |
| RBSP_EFW_SYS_001 | EFW Systems Requirements |

## 1 Introduction

This document outlines the Data Controller Board (DCB) for the Electric Field and Waves (EFW) instrument on the Radiation Belt Storm Probes (RBSP) mission. It defines the components and basic functionality of the board. Further details are contained in the FPGA specification (RBSP_EFW_DCB_001) and the Flight Software specification (RBSP_EFW_FSW_001). Two flight boards will be built, along with a spare board (TBD), an engineering board and breadboard.

## 2 Requirements

The EFW instrument requirements are found in RBSP_EFW_SYS_001. The requirements pertaining to the DCB board are listed below for reference. The up to date list found in RBSP_EFW_SYS_001 remains the master document when referencing requirements. Requirement for the FSW are not listed here.

| ID | Req. Title | Subject | Priority | Requirement Body or Section Heading |
| :--- | :--- | :--- | :--- | :--- |
| EFW- <br> 81 | EFW Command | The EFW <br> IDPU | shall | accept commands via serial interface |
| EFW- <br> 82 | EFW Telemetry Rate | The EFW <br> IDPU | shall | generate a continuous, serial telemetry stream at a rate not to exceed 12,000 <br> bps. |
| EFW- <br> 83 | EFW Telemetry Peak | The EFW <br> IDPU | shall | limit the instantaneous data rate to the spacecraft to $\leq 80 \mathrm{kbps}$ |
| EFW- <br> 84 | EFW Telemetry <br> Compression | The EFW <br> IDPU | shall | perform data compression |
| EFW- <br> 85 | EFW use of MET | The EFW <br> IDPU | shall | use Mission Elapsed Time (MET) as the reference time for time stamps <br> produced for science, space weather, and instrument housekeeping data. |
| EFW- <br> 86 | EFW MET <br> Acceptance | The EFW <br> IDPU | shall | accept the distribution of MET from its respective spacecraft at a frequency <br> of 1 Hz. |
| EFW- <br> 87 | EFW Serial Interface | The EFW <br> IDPU | shall | accommodate a standard point-to-point serial interface for data exchange <br> with the spacecraft. |
| EFW- <br> 92 | EFW Engineering <br> Mode | The EFW <br> IDPU | shall | provide an Engineering Mode for deployments |
| EFW- <br> 93 | EFW Normal Mode | The EFW <br> IDPU | shall | provide a Normal Mode for science data collection |
| EFW- <br> 94 | EFW Burst Mode | The EFW <br> IDPU | shall | provide a Burst Mode for high speed collections |
| EFW- <br> 96 | EFW Illegal <br> Commands | The EFW <br> IDPU | shall | validate commands prior to execution. |
| EFW- <br> 97 | EFW Data Integrity | The EFW <br> IDPU | shall | detect and correct data errors in its Solid State Recorder. |
| EFW- <br> 133 | EFW EMI/EMC <br> Capabilities | The EFW <br> Suite | The EFW <br> Suite | shall |
| EFW- <br> 137 | EFW Quality <br> Assurance | Electromagnetic Environment Control Plan, APL document no. 7417-9018. <br> modified by the Compliance Matrix |  |  |

## 3 Block Diagram

The DCB board block diagram is shown in figure 1 below.



Figure 1: DCB Block Diagram

## 4 Functional Overview

The Data Controller Board (DCB) houses the EFW instrument processor (Z80) inside a RTAX2000S Actel using a CAST Inc IP core. This Actel also houses the control logic that interfaces to the spacecraft, other instrument boards and on card memory. Boot software, stored in PROM ( 32 kB ) and patchable EEPROM ( 128 kB ) software is based on many UCB EFW instruments including those for THEMIS, FAST and POLAR. Software is copied from PROM and EEPROM to run in SRAM (128kB). The board also has SDRAM (256MB) and Flash Memory (32GB) for storage of science data, and an ADC for digitization of housekeeping quantities.

### 4.1 Science Data Collection \& Transmission

Data is acquired from the Digital Fields Board (DFB) and stored in SDRAM by using DMA channels in the FPGA. Data is packetized here inside 4 kB memory segments before being transferred to the spacecraft memory or to flash memory. Survey data is either held in the SDRAM or immediately telemetered to the spacecraft. The Burst data is either held in the SDRAM or stored in the flash memory. The flash memory is composed of 8 parts, each of 4GB that are switched individually to isolate the memory parts from each other and the rest of the DCB circuit. A high signal from the FPGA enables the switch to each device.

When the flash memory is powered to transfer data in or out, the FPGA will take steps to try to ensure that the transfer is completed successfully. Firstly the device will be reset. Data being read from the device will be have data checked using an ECC algorithm with the corresponding

checkbits. These are stored in the flash control bits internal to the flash memory. For write cycles the FPGA will generate the ECC bits and write them to the control bits in the flash memory along with the data, and provide option for post program verification. Data stored in the flash memory is transferred to the SDRAM first if it is to be telemetered to the spacecraft. Data will be compressed here by FSW if necessary before it is sent out on the spacecraft interface. Details of the compression scheme will be found in the FSW specification.

Analog housekeeping values will be digitized by a single ADC. A multiplexer will provide the switched voltages to the ADC that is controlled by the FSW through the FPGA logic. More information is detailed in the ADC section below.

### 4.2 Memory Buses

There are 4 buses on the board:

1. CPU Bus

Internal to the FPGA. This is used by the CPU only but interfaces with the memory bus with the FPGA logic acting as bus arbitrator.
2. Memory Bus

PROM, EEPROM, SRAM and the ADC sit on this bus.
3. SDRAM Bus

The SDRAM has it's own private bus that is controller by the FPGA logic.
4. Flash Bus

The Flash memory has it's own private bus that is controlled by the FPGA logic.

### 4.3 Memory Map

See RBSP_EFW_DCB_001 (FPGA Specification) for details.

### 4.4 Power

The DCB board requires the following power supplies: $+1.8 \mathrm{VD},+3.6 \mathrm{VD},+5 \mathrm{VD},+5 \mathrm{VA},-5 \mathrm{VA}$, $+10 \mathrm{VA},-10 \mathrm{VA}$. Table below shows the breakdown of current consumption by major component. These numbers are estimates and will be updated when current consumption is measured on the breadboard / engineering unit. The 1.8 VD supply will be regulated down to 1.5 VD for the Actel. The 3.6 VD supply will be regulated down to 3.3 VD . Where there is a current protection switch an LDO will also be implemented for that supply. See section below on current protection.

| Component | Manufacturer | Part No | Quantity | Supply (V) | Peak Icc (mA) | Avg Icc(mA) | Peak Total (mW) | Average Total (mW) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| FPGA | Actel | RTAX2000S | 1 | 3.3 | 27 | 24 | 90 | 80 |
| FPGA | Actel | RTAX2000S | 1 | 1.5 | 373 | 187 | 560 | 280 |
| Prom | BAE | 238A790 | 1 | 3.3 | 19 | 0 | 63 | 0 |
| EEProm | Maxwell | 28LV010 | 1 | 3.3 | 25 | 0 | 84 | 0 |
| SRAM | Honeywell | HLX6228 | 1 | 3.3 | 36 | 36 | 120 | 120 |
| SDRAM | 3d-Plus | MMSD08256804S-C-1S | 1 | 3.3 | 200 | 50 | 660 | 165 |
| Flash | 3d-Plus | MMFN08408808S-F-1S | 8 | 3.3 | 40 | 0 | 132 | 0 |
| Buffers | Aeroflex | UT54ACS164245SEI | 18 | 3.3 | 10 | 5 | 297 | 149 |
| ADC | Linear | LTC1604 | 1 | 5 | 18 | 1 | 90 | 5 |
| ADC | Linear | LTC1604 | 1 | -5 | 26 | 1 | 130 | 5 |
| Mux | Intersil | HI-0508 | 1 | 10 | 1 | 0.5 | 10 | 5 |
| Mux | Intersil | HI-0508 | 1 | -10 | 1 | 0.5 | 10 | 5 |
| LVDS Receiver | Aeroflex | UT54LVDS032LV | 1 | 3.3 | 15 | 15 | 50 | 50 |
| LVDS Driver | Aeroflex | UT54LVDS031LV | 1 | 3.3 | 18 | 18 | 59 | 59 |


| Total Power |  |  | 2236 |  | 923 |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Total 3.3V Current |  | 391 | 149 |  |  |
| Total 1.5V Current |  | 373 | 187 |  |  |
|  | Regulator Po |  |  |  |  |
|  | 3.3 V in mW | 117.4 | 44.6 |  |  |
|  | 1.5 in mW | 112.0 | 56.0 |  |  |

## 5 Component Description

### 5.1 Processor

The DCB uses a IP core implementation of a Z80 processor inside an Actel RT2000S FPGA. The core, from CAST Inc, will run at $16.777 \mathrm{MHz}\left(2^{24} \mathrm{~Hz}\right)$ driven by an on card oscillator. A full description of the core is contained in RBSP_EFW_DCB_002.

### 5.2 Actel FPGA

The Actel FPGA is a 352 pin CQFP RTAX2000S part. For the breadboard a commercial AP1000S reprogrammable part is used instead. The engineering board will use the Aldec board that has an Actel A3EP1500 part on an adaptor board that fits the CQFP-352 footprint of the flight part. A prototype RTAX2000S will be used once the design is sufficiently mature. The external oscillator clocks the FPGA logic that glues the processor with the memory and external interfaces at the same frequency as the processor. A full description of the FPGA specification is described in RBSP_EFW_DCB_001.

### 5.3 Spacecraft Interface

The DCB board provides the digital interface to the spacecraft, receiving commands and sending science and housekeeping telemetry. The protocol for this is LVDS, using Aeroflex parts UT54LVDS031LV and UT54LVDS032LV to drive the interface. The breadboard DCB uses the same driver parts as on the APL provided GSE (TI pn\#SN65LVDM176). The six line interface comprises of three differential signals - command, telemetry and $1 \mathrm{~Hz} /$ SpinPulse. The command and telemetry interface run at 115.2 kbaud. Commands can be received at any time during the first 950 ms after the 1 Hz tick. Telemetry can be sent at any time in the first 950 ms after the 1 Hz tick. More detailed information is contained in the EFW ICD (APL Document 7417-9083).

### 5.4 Reset

A power on reset (POR) circuit provides a global board reset signal to the FPGA. The FPGA should double clock the active low signal before triggering a reset. The POR is Or'd together with a watchdog reset register inside the FPGA. If the software does not write to the watchdog register every 3 seconds a reset will be triggered. The watchdog can be disabled using an external FPGA pin tied to ground. A FSW command resets the FSW only - and is detailed in the FSW specification (RBSP_EFW_FSW_001).

### 5.5 PROM

The flight board has a single 32k x 8bit PROM memory from BAE Systems (pn\#238A790). This will store the standard boot FSW code. Both parts are housed in a 28 pin flatpack package. For the breadboard design the prom will be replaced by a 128 k x 8 EEPROM (ATMEL pn\#AT28LV010) that can be programmed via the serial interface provided or via the spacecraft interface once boot code is running. Jumpers on the breadboard provide for segmentation of the device into 4 blocks. The engineering board is likely to have a socket for both the dual inline packaged EEPROM (AT28BV256) and the flatpack PROM. Initial board testing will be done with the EEPROM, which will be replaced with the programmed PROM part when FSW is ready. Note that to program the 3.3 V Atmel EEPROM a security code is required to unlock the device (i.e. the write protect function is always enabled).

### 5.6 EEPROM

A 128k x 8bit EEPROM from Maxwell will provide space for patches and storage of instrument configuration scripts (pn\#28LV010). For the breadboard the ATMEL equivalent part will be used (pn\#AT28LV010). The part for the engineering model is the engineering version of the Maxwell part.

### 5.7 SRAM Memory

The flight board will have a single 128k x 8 SRAM part from Honeywell (pn\#HLX6228). The breadboard uses an equivalent 128k x 8 part from ISSI (pn\#IS62WV1288BLL). The part for the engineering model is the engineering version of the Honeywell part.

### 5.8 Serial Flash

There is the option to install a serial flash $64 \mathrm{k} \times 8$ part on the breadboard (ST pn\#M25P05A). This would allow up or down load of data via a SPI USB interface to a PC using a dediprog device (http://www.dediprog.com/product.php?UID=2).

### 5.9 SDRAM

A single 256MByte SDRAM module provides the storage for telemetry from the DFB before it is telemetered to the spacecraft or stored in the Flash memory. The part (3d-Plus pn\#MMSD08256804S-C ) operates on a single 3.3 V switched supply. The part meets the latch up requirement and therefore does not need an overcurrent protection circuit. However the part does have a power switch for flexibility. The SDRAM resides on a private memory bus that is buffered (TBD).

### 5.10 Flash Memory

Eight 32Gbit NAND Flash memory parts are used for storage of burst telemetry data. The parts are 50 pin SOP packaged parts, that have $3 \mathrm{Vcc}(3.3 \mathrm{~V})$ pins and 4 ground pins. $8 \mathrm{I} / \mathrm{O}$ pins are used to transfer data and commands and the other pins provide control to the device. As the flash memory has a relative high incidence of SEFI and SEU effects (see proton affects TN16) it is recommended to keep the parts unpowered except when a read or write to the device occurs. Each flash parts will require $11 / 216$ bit buffers, 1 buffer drives the chip enable (CE) pins and other control signals and the other buffer drives the I/O pins for two flash modules. The flash memory will be powered on writing to a register in the FPGA. Although flash memory can be programmed bit by bit it is much more efficient to program it in pages $(2 \mathrm{kB})$ or blocks ( 128 kB ).

### 5.11 ADC

A single LTC1604 ADC provides the digitalization of analog housekeeping for the instrument. The BEB and PCB housekeeping lines are multiplexed with the DCB housekeeping signals into the ADC. Table 1 provides the Analog HK decoding on the DCB. All inputs shall be between 2.5 V and +2.5 V . The digital side of the ADC sits on the memory bus (MEMBUS) controlled by the FPGA. The conversion time is controlled by a write to a register in the FPGA and the data is made available at address $0 x 40000$ after conversion (see memory map for details). The ADC requires $+5 \mathrm{VA},+5 \mathrm{VD}$ and -5 VA .. To conserve power the ADC should kept in nap mode when the CPU is not requesting a conversion. The CPU should allow 500us for the voltage to settle at the output of the analog mux following a channel switch prior to performing a conversion.

| MUX | HK Name | HK Function |
| :---: | :--- | :--- |
| 0 | PCB_HK | PCB Housekeeping Line |
| 1 | BEB_HK | BEB Housekeeping Line |
| 2 | TEMP_FPGA | FPGA Temperature |
| 3 | P33VD | 3.3V Voltage Monitor |
| 4 | P33IMON | $3.3 V$ Current Monitor |
| 5 | P15VD | $1.5 V$ Voltage Monitor |
| 6 | P15IMON | 1.5V Current Monitor |
| 7 | DGND | Digital Ground |

Table 1

### 5.12 Current Protection Circuit and Low Dropout Regulator

There is no hardware controlled current protection for any individual DCB component. The 3.6 VD and 1.8 VD supplies have current monitors that are available for sampling by the FSW.

A radiation hardened LDO regulator is implemented on the 3.6 VD and 1.8 VD supplies from MS
Kennedy (part number MSK5822-3.3RH and MSK5822-1.5RH).

### 5.13 Backplane Interface

The DCB communicates with the DFB using an all 3.3 V interface. 3.3 V 54 AC 14 devices provide buffering to the backplane. The DCB sends commands to the DFB and receives science and housekeeping telemetry. The DCB also communicates with the LVPS/PCB and the BEB boards using a 5 V interface. Aeroflex part UT54ACS164245SEI provides the level shifting and buffering to these two boards. More details about the interface can be found in the RBSP EFW backplane specification (RBSP_EFW_BPL_001).
The BEB requires a series of DAC commands to be sent to the board when DAC settings are changed. There are 20 DAC commands in total and they are stored in registers in the DCB FPGA. FSW writes to a register in the FPGA to send the commands to the BEB. More information is contained in the DCB FPGA specification (RBSP_EFW_DCB_001).

### 5.14 Buffers

Where necessary the following device will be used on the flight board. http://ams.aeroflex.com/ProductFiles/DataSheets/MSI/msi16245SSEI.pdf This provides level shifting (from 3.3 V to 5 V ) and buffering of signals to memory, ADC and the backplane where necessary.

### 5.15 Debug Board

A separate debug board is used for check out and FSW testing of the DCB board. It contains a EEPROM, switches, LEDs and Logic Analyzer connections. The as built schematic is drawing number RBSP_EFW_DCB_005C.

## 6 Layout requirements

The DCB circuit is populated on a 6 U VME card. The highest component is the 3d-Plus Flash memory module ( 11.93 mm high). The envelope for the components on the card is detailed in the backplane specification (RBSP_EFW_BPL_001). IC components will go on the top of the board, passive components on the bottom.

The board mechanical drawing (RBSP-IDP-MEC-011 REV F DCB PCB OUTLINE.pdf) shows keep out areas and spacing of connectors and mounting holes.

## 7 Connectors

The DCB has three connectors. One connects to the Spacecraft, one to the other IDPU boards and the other is used for debugging and test and is not connected after instrument delivery to APL.

### 7.1 Spacecraft Data Interface

The DCB connects to the spacecraft C\&DH via a single 9 pin D male sub connector. The pin out is listed in Table 2 below. The protocol for communication with the spacecraft is listed in the EFW ICD (APL-7417-9083).

| Pin \# |  | Signal Name |
| :---: | :--- | :--- |
| 1 | PSS/SP_P | 1 Hz \& Sun Pulse Positive |
| 2 | - | NC |
| 3 | TC_N | Telecommand Negative |
| 4 | TLM_P | Telemetry Positive |
| 5 | DGND | Digital Ground |
| 6 | 1PS/SP_N | 1Hz \& Sun Pulse Negative |
| 7 | TC_P | Telecommand Positive |
| 8 | - | NC |
| 9 | TLM_N | Telemetry Negative |

Table 2: S/C Connector pin out

### 7.2 Backplane Power \& Data Interfaces

The DCB communicates with the other IDPU boards via the backplane. It also receives power from the LVPS/PCB board on the same connector. The pins used on the backplane connector are listed in Table 3 below. The connector is a Hypertronics KA98/127 style connector.

| BKP <br> Pin \# | Signal Name | Signal Function |
| :---: | :--- | :--- |
| 1 | DFB_CMD | DFB Command |
| 2 | DFB_CLK | DFB Clock |
| 3 | DFB_TLM0 | DFB Telemetry Line0 |
| 4 | DFB_CMD | DFB Command |
| 5 | DFB_1HZ | DFB 1Hz |
| 6 | DFB_TLM1 | DFB Telemetry Line1 |
| 7 | DFB_CLK | DFB Clock |
| 8 | DFB_1HZ | DFB 1Hz |
| 9 | DIG_SPARE9 | Spare |
| 10 | PCB_CMD | PCB Command |
| 11 | DIG_SPARE11 | Spare |
| 12 | BEB_ACTEST2 | BEB Actest Line2 |

Electric Fields and Waves


Table 3: Backplane Interface Connections

### 7.3 Debug Interface

The Breadboard DCB contains all the debugging connections on the board through numerous 20 pin headers surrounding the Actel FPGA part. The engineering and flight units will not have these headers on the board. There will be a single MDM 51S connector that provides an interface to a debug board that can be connected while the board is installed in the IDPU chassis.

| MDM Pin \# | Signal Name |
| :---: | :---: |
| 1 | DGND |
| 2 | MEMADDR0 |
| 3 | MEMADDR1 |
| 4 | MEMADDR2 |
| 5 | MEMADDR3 |
| 6 | MEMADDR4 |
| 7 | MEMADDR5 |
| 8 | MEMADDR6 |
| 9 | MEMADDR7 |
| 10 | MEMADDR8 |
| 11 | MEMADDR9 |
| 12 | MEMADDR10 |
| 13 | MEMADDR11 |
| 14 | MEMADDR12 |
| 15 | MEMADDR13 |
| 16 | MEMADDR14 |
| 17 | MEMADDR15 |
| 18 | MEMADDR16 |
| 19 | MEMDATA0 |
| 20 | MEMDATA1 |
| 21 | MEMDATA2 |
| 22 | MEMDATA3 |
| 23 | MEMDATA4 |
| 24 | MEMDATA5 |
| 25 | MEMDATA6 |
| 26 | MEMDATA7 |
| 27 | DGND |
| 28 | MBUSCYTYPEO |
| 29 | MBUSCYTYPE1 |
| 30 | MBUSCYTYPE2 |
| 31 | MBUSCYTYPE3 |
| 32 | MISCCTRLO |
| 33 | MISCCTRL1 |
| 34 | MISCCTRL2 |



| 35 | MISCCTRL3 |
| :--- | :--- |
| 36 | MISCCTRL4 |
| 37 | MISCCTRL5 |
| 38 | MISCCTRL6 |
| 39 | MISCCTRL7 |
| 40 | MISCCTRL8 |
| 41 | MISCCTRL9 |
| 42 | MISCCTRL10 |
| 43 | MISCCTRL11 |
| 44 | LASTROBE0 |
| 45 | LASTROBE1 |
| 46 | LASTROBE2 |
| 47 | NMI |
| 48 | DEBUG_nRESET |
| 49 | RxD |
| 50 | TxD |
| 51 | P3.3VD |

## 8 Commands

Commands are contained in the command and Telemetry document RBSP_EFW_FSW_005_CTM.

